

# 2.5V Drive Nch+Pch MOSFET

## QS6M4

●Structure

Silicon P-channel MOSFET  
Silicon N-channel MOSFET

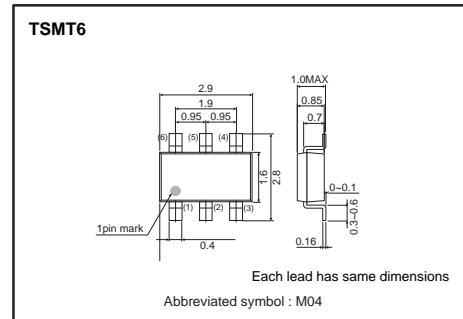
●Features

- 1) The QS6M4 combines Pch MOSFET with a Nch MOSFET in a single TSMT6 package.
- 2) Low on-state resistance with a fast switching.
- 3) Low voltage drive (2.5V).

●Applications

Load switch, inverter

●Dimensions (Unit : mm)



●Packaging specifications

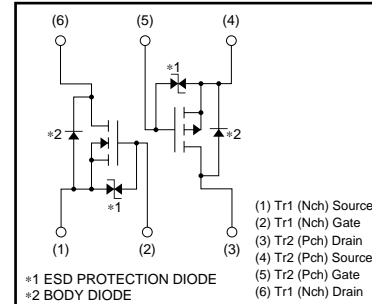
Type	Package	Taping
	Code	TR
	Basic ordering unit (pieces)	3000
QS6M4		○

●Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Limits		Unit
		Nchannel	Pchannel	
Drain-source voltage	$V_{DS}$	30	-20	V
Gate-source voltage	$V_{GS}$	±12	±12	V
Drain current	Continuous	$I_D$	±1.5	A
	Pulsed	$I_{DP}^{*1}$	±6.0	A
Source current (Body diode)	Continuous	$I_S$	0.8	A
	Pulsed	$I_{SP}^{*1}$	6.0	A
Total power dissipation	$P_D^{*2}$	1.25		W / TOTAL
		0.9		W / ELEMENT
Channel temperature	$T_{ch}$	150		°C
Storage temperature	$T_{stg}$	-55 to +150		°C

\*1  $P_w \leq 10\mu s$ , Duty cycle  $\leq 1\%$   
\*2 Mounted on a ceramic board

●Equivalent circuit



●Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	$R_{th}(ch-a)^{*}$	100	°C / W / TOTAL
		139	°C / W / ELEMENT

\* Mounted on a ceramic board

Transistors

●Electrical characteristics (Ta=25°C)

<Tr1. N-ch MOSFET>

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	-	-	±10	μA	V <sub>GS</sub> =±12V / V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR) DSS</sub>	30	-	-	V	I <sub>D</sub> =1mA / V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	-	-	1	μA	V <sub>DS</sub> =30V / V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS (th)</sub>	0.5	-	1.5	V	V <sub>DS</sub> =10V / I <sub>D</sub> =1mA
Static drain-source on-state resistance	R <sub>DS (on)</sub> *	-	170	230	mΩ	I <sub>D</sub> =1.5A / V <sub>GS</sub> =4.5V
		-	180	245		I <sub>D</sub> =1.5A / V <sub>GS</sub> =4.0V
		-	260	360		I <sub>D</sub> =1.0A / V <sub>GS</sub> =2.5V
Forward transfer admittance	Y <sub>fs</sub>   *	1.0	-	-	S	V <sub>DS</sub> =10V / I <sub>D</sub> =1.0A
Input capacitance	C <sub>iss</sub>	-	80	-	pF	V <sub>DS</sub> =10V
Output capacitance	C <sub>oss</sub>	-	25	-	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	-	15	-	pF	f=1MHz
Turn-on delay time	t <sub>d (on)</sub> *	-	7	-	ns	I <sub>D</sub> =1A, V <sub>DD</sub> =15V
Rise time	t <sub>r</sub> *	-	18	-	ns	V <sub>GS</sub> =4.5V
Turn-off delay time	t <sub>d (off)</sub> *	-	15	-	ns	R <sub>L</sub> =15Ω / R <sub>G</sub> =10Ω
Fall time	t <sub>f</sub> *	-	15	-	ns	
Total gate charge	Q <sub>g</sub> *	-	1.6	-	nC	V <sub>DD</sub> =15V R <sub>L</sub> =10Ω
Gate-source charge	Q <sub>gs</sub> *	-	0.5	-	nC	V <sub>GS</sub> =4.5V R <sub>G</sub> =10Ω
Gate-drain charge	Q <sub>gd</sub> *	-	0.9	-	nC	I <sub>D</sub> =1.5A

\*Pulsed

●Body diode characteristics (Source-Drain)

<Tr1. N-ch MOSFET>

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V <sub>SD</sub> *	-	-	1.2	V	I <sub>S</sub> =3.2A / V <sub>GS</sub> =0V

\*Pulsed

Transistors

●Electrical characteristics (Ta=25°C)

<Tr2. P-ch MOSFET>

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	-	-	±10	μA	V <sub>GS</sub> = ±12V / V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR) DSS</sub>	-20	-	-	V	I <sub>D</sub> = -1mA / V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	-	-	-1	μA	V <sub>DS</sub> = -20V / V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS(th)</sub>	-0.7	-	-2.0	V	V <sub>DS</sub> = -10V / I <sub>D</sub> =-1mA
Static drain-source on-state resistance	R <sub>DS(on)</sub> *	-	155	215	mΩ	I <sub>D</sub> = -1.5A / V <sub>GS</sub> = -4.5V
		-	170	235		I <sub>D</sub> = -1.5A / V <sub>GS</sub> = -4.0V
		-	310	430		I <sub>D</sub> = -0.75A / V <sub>GS</sub> = -2.5V
Forward transfer admittance	Y <sub>fs</sub>   *	1.0	-	-	S	V <sub>DS</sub> = -10V / I <sub>D</sub> = -0.75A
Input capacitance	C <sub>iss</sub>	-	270	-	pF	V <sub>DS</sub> = -10V
Output capacitance	C <sub>oss</sub>	-	40	-	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	-	35	-	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *	-	10	-	ns	I <sub>D</sub> = -0.75A, V <sub>DD</sub> = -15V
Rise time	t <sub>r</sub> *	-	12	-	ns	V <sub>GS</sub> = -4.5V
Turn-off delay time	t <sub>d(off)</sub> *	-	45	-	ns	R <sub>L</sub> =20Ω / R <sub>G</sub> =10Ω
Fall time	t <sub>f</sub> *	-	20	-	ns	
Total gate charge	Q <sub>g</sub> *	-	3.0	-	nC	V <sub>DD</sub> = -15V R <sub>L</sub> =10Ω
Gate-source charge	Q <sub>gs</sub> *	-	0.8	-	nC	V <sub>GS</sub> = -4.5V R <sub>G</sub> =10Ω
Gate-drain charge	Q <sub>gd</sub> *	-	0.85	-	nC	I <sub>D</sub> = -1.5A

\*Pulsed

●Body diode characteristics (Source-Drain)

<Tr2. P-ch MOSFET>

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V <sub>SD</sub>	-	-	-1.2	V	I <sub>S</sub> = -0.75A / V <sub>GS</sub> =0V

Transistors

N-ch

● Electrical characteristic curves

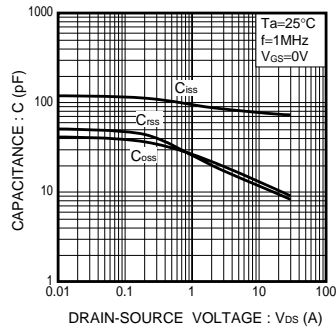


Fig.1 Typical Capacitance vs. Drain-Source Voltage

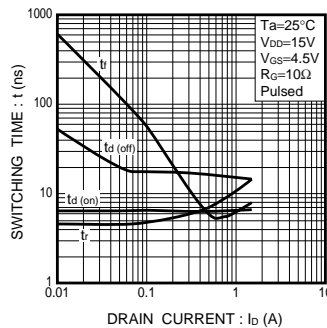


Fig.2 Switching Characteristics

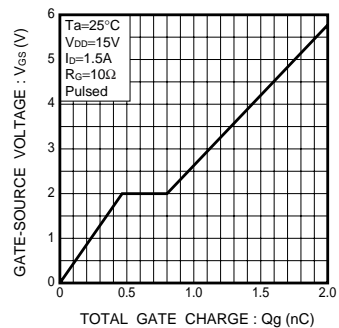


Fig.3 Dynamic Input Characteristics

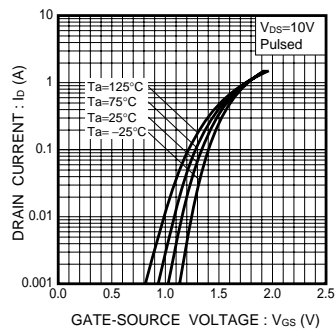


Fig.4 Typical Transfer Characteristics

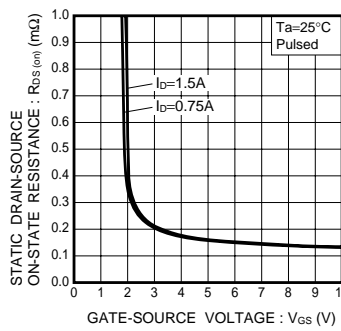


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

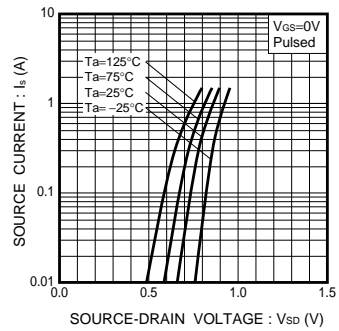


Fig.6 Source Current vs. Source-Drain Voltage

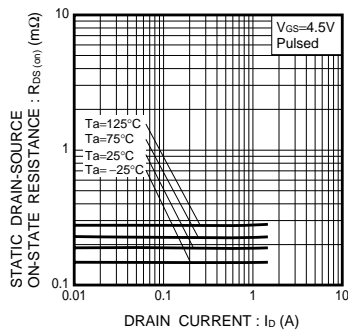


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (I)

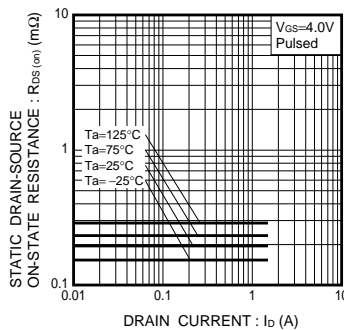


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (II)

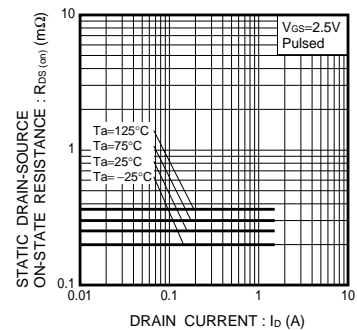


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current (III)

Transistors

P-ch

● Electrical characteristic curves

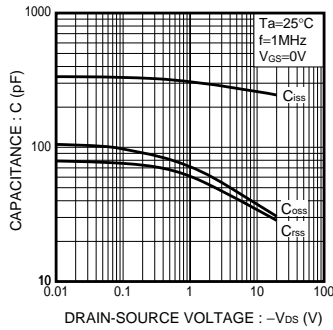


Fig.1 Typical Capacitance vs. Drain-Source Voltage

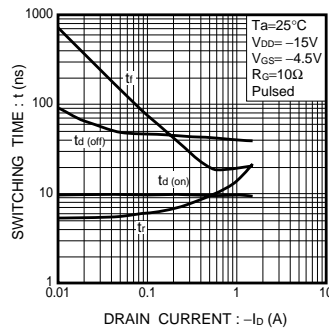


Fig.2 Switching Characteristics

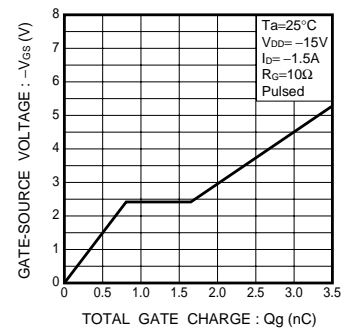


Fig.3 Dynamic Input Characteristics

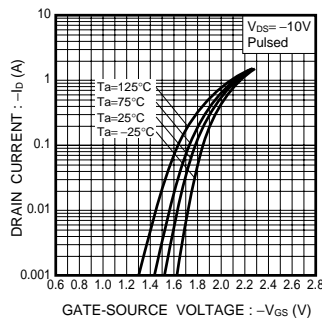


Fig.4 Typical Transfer Characteristics

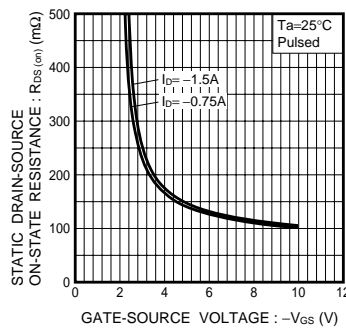


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

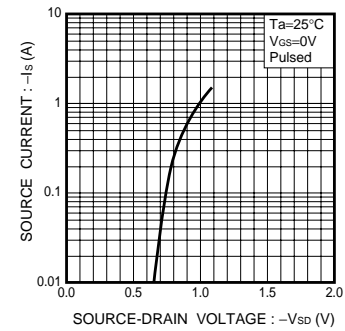


Fig.6 Source Current vs. Source-Drain Voltage

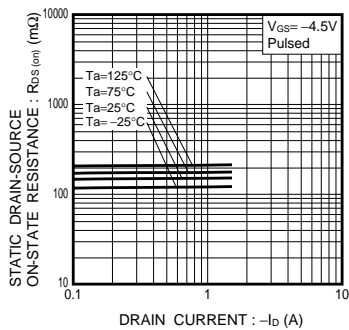


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (I)

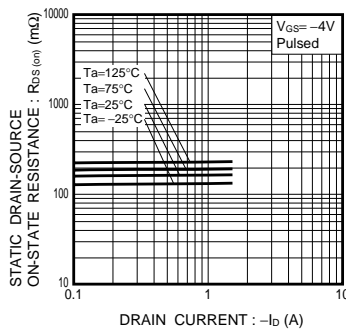


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (II)

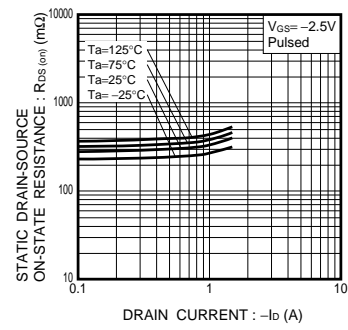


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current (III)

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